



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of  
Kenichi HAMANAKA et al.  
Serial No.: 09/854,767  
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#2 J. White

For: ADHESIVE RESIN COMPOSITION AND METHOD OF PRODUCING THE SAME,  
AND CHIP COIL COMPONENT

Asst. Commissioner of Patents and Trademarks  
Washington, D.C. 20231

SUBMISSION

Sir:

Submitted herewith is a copy of art together with a form listing the same for the convenience of the Examiner. The enclosed document is described on page 2 of the specification.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee due during the pendency of this application is not paid, the patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on June 20, 2001

Respectfully submitted,

James A. Finder Esq.

Name of applicant, assignee or  
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Signature  
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Enclosure